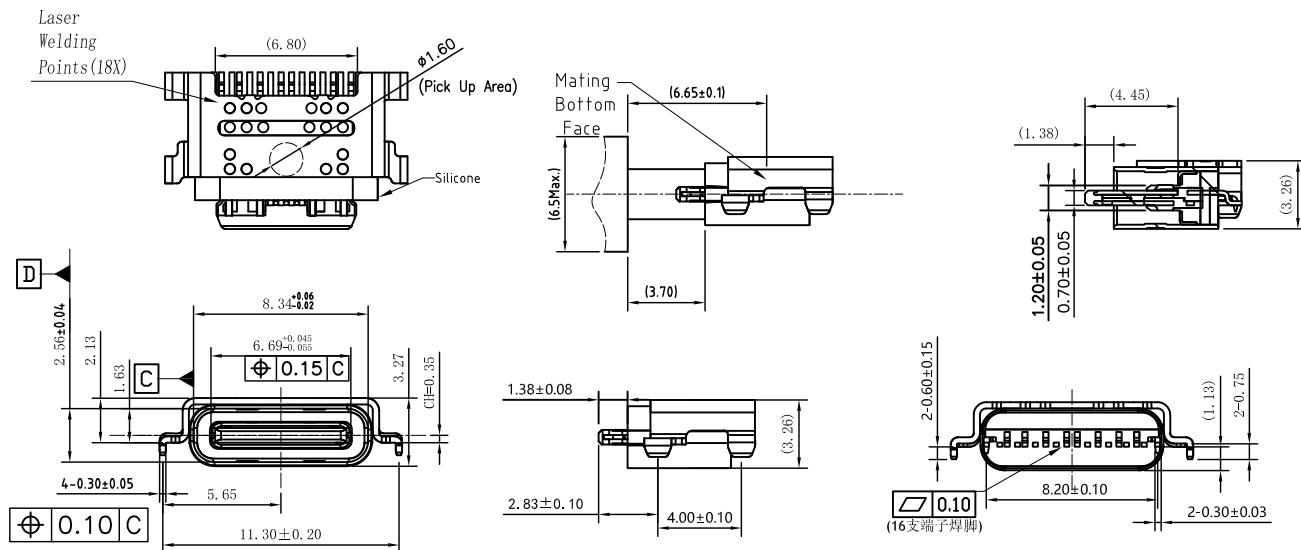


NOTES:

1.MATERIAL SPECIFICATION:

- 1-1.HOUSING:High-Temp Plastics,UL94V-0,Color:Black.
- 1-2.CONTACTS:Copper Alloy $T=0.25\text{mm}$.
- 1-3.OUTER SHELL:Stainless Steel, $T=0.30\text{mm}$.
- 1-4.INNER SHELL:Stainless Steel, $T=0.20\text{mm}$.
- 1-5.MID-PLATE:Stainless Steel, $T=0.20\text{mm}$.
- 1-6.SOLDER-PLATE:Stainless Steel, $T=0.10\text{mm}$.

2.PLATING SPECIFICATION:

- 2-1.CONTACTS:
Ni UNDERPLATED OVER ALL;
Gold Plated On Contact Area;
Gold Flash Plated On Solder Area.

- 2-2.SHELL:
Ni UNDERPLATED OVER ALL;
Gold Flash Plated ON Solder Leg.

3.RoHS AND HF COMPLIANT.

4.MECHANICAL PERFORMANCE:

- 4-1.MATING FORCE: $6 \sim 20\text{N}$ (Initial); $5 \sim 20\text{N}$ (After)
- 4-2.UNMATING FORCE: $8 \sim 20\text{N}$ (Initial); $6 \sim 20\text{N}$ (After)
- 4-3.DURABILITY:10000 CYCLES.

5.ELECTRICAL PERFORMANCE:

- 5-1.CURRENT RATING:3A;VOLTAGE RATING:5.0V
- 5-2.LLCR:

VBUS & GND PINS:40mΩH/PIN MAX.;
OTHERS PINS:40mΩH/PIN MAX.;
LLCR MAX. CHANGE OF ALL PINS:20mΩE.

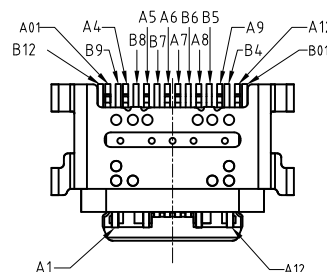
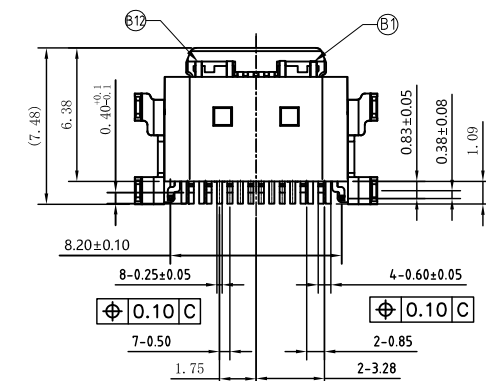
- 5-3.INSULATION RESISTANCE:100MΩ MIN.
- 5-4.DIELECTRIC WITHSTANDING VOLTAGE:
100V AC FOR 1 MINUTE.

6.ENVIROMENTAL PERFORMANCE:

OPERATING TEMPERATURE: $-20^{\circ}\text{C} \sim +85^{\circ}\text{C}$.

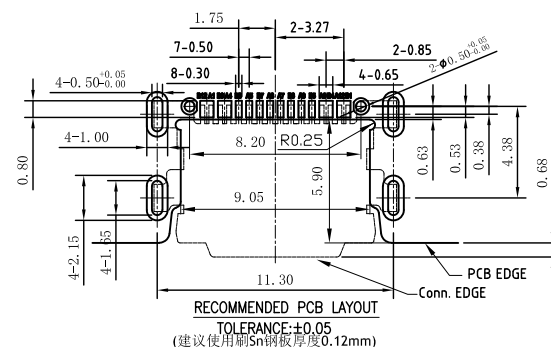
7.RECOMMENDED PROCESS:

THE PEAK TEMPERATURE ON THE BOARD
SHALL MAINTAIN 10 ± 1 SECONDS AT $255 \pm 5^{\circ}\text{C}$.



Pin Assignments

Contact Number	Signal Name	Contact Number	Signal Name
A1	GND	B12	GND
A4	VBUS	B9	VBUS
A5	CC1	B8	SBU2
A6	Dp1	B7	Dn2
A7	Dn1	B6	Dp2
A8	SBU1	B5	CC2
A9	VBUS	B4	VBUS
A12	GND	B1	GND



深圳市华宇创精密电子有限公司

TOLERANCE:

X.X ± 0.30
X.XX ± 0.25
X.XXX ± 0.15

X' $\pm 2^{\circ}$ X.X' $\pm 0.5^{\circ}$

UNIT: mm [inch]

SCALE:1:1 SIZE: A4

DRAWN BY :

陈一鸣

DATE :

2014-02-23

PART NAME:

USB TYPE C 防水母座16P 沉板1.13

CHECKED BY:

马跃

DATE :

2014-02-23

PART NO.

HYCW394-USBC16-113B

MOLD NO.

APPROVED BY:

邱敏

DATE :

2014-02-23

DRAW NO:

HYC-2212101804

SHEET NO.

1 OF 1